

Title (en)  
TEMPERATURE MANAGING FOR ELECTRONIC COMPONENTS

Title (de)  
TEMPERATURVERWALTUNG FÜR ELEKTRONISCHE BAUTEILE

Title (fr)  
GESTION DE TEMPÉRATURE DE COMPOSANTS ÉLECTRONIQUES

Publication  
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Application  
**EP 06747851 A 20060602**

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Abstract (en)  
[origin: WO2007142558A1] The invention provides a temperature managing arrangement (100, 200) comprising; a reservoir (240) arranged to accumulate a tempering liquid (242); a pressurizing device (210) arranged to pressurise the tempering liquid (242); at least one spray module (220) arranged to receive the pressurized liquid (242) and comprising at least one spraying device (222) arranged to spray the liquid (242) on at least one electronic component (224) so as to create a thermal coupling between the sprayed liquid (242) and the component (224); a heat remover (230) arranged to cool the tempering liquid (242), being in at least one of a liquid, a vapor or a mist form after spraying, when thermal energy is to be removed from said component (224); and wherein said tempering managing arrangement (200) is further comprising a heating device (245) arranged to heat the tempering liquid (242) before spraying when thermal energy is to be provided to said component (224). In addition, the invention provides a method for using said temperature managing arrangement.

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